

MINI MELF Glass-Encapsulate Diodes

Small Signal Fast Switching Diodes

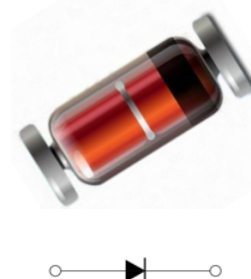
Features

- High reliability
- Low reverse current and low forward voltage

Applications

- Low current rectification and high speed switching

MINI MELF(SOD-80/ LL- 34)



极限值和温度特性(TA = 25℃ 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value		单位 Unit
		LL60	LL60P	
最高反向电压 Peak Reverse Voltage	VRM	40	45	V
最高正向电流 Peak Forward Current	IFM	150		mA
平均整流输出电流 Average Rectified Output Current	Io	50		mA
正向浪涌电流 Surge Forward Current	ISURGE	500		mA
存储温度 Storage temperature	Ts	-55-+170		℃
工作结温度 Operating Junction Temperature	Tj	125		℃

电特性 (TA = 25℃ 除非另有规定)

Electrical Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified).

符号 Symbols	参数 Parameter	测试条件 Test Condition		Limits		单位 Unit
				Min	Max	
IR	反向漏电流 Reverse Leakage Current	VR=15V	LL60	---	0.5	uA
			LL60P	---	1	
VF	正向电压 Forward Voltage	IF=1mA	LL60	---	0.5	V
			LL60P	---	0.5	
		IF=30mA	LL60	---	1.0	
		IF=100mA	LL60P	---	1.0	
TRR	反向恢复时间 Reverse Recovery Time	IF=IR=1mA RL=100Ω IRR=1mA		---	1	nS
CJ	结电容 Junction Capacitance	VR=1V, f=1MHZ	LL60	---	2	pF
		VR=10V, f=1MHZ	LL60P		6	

Typical Characteristics

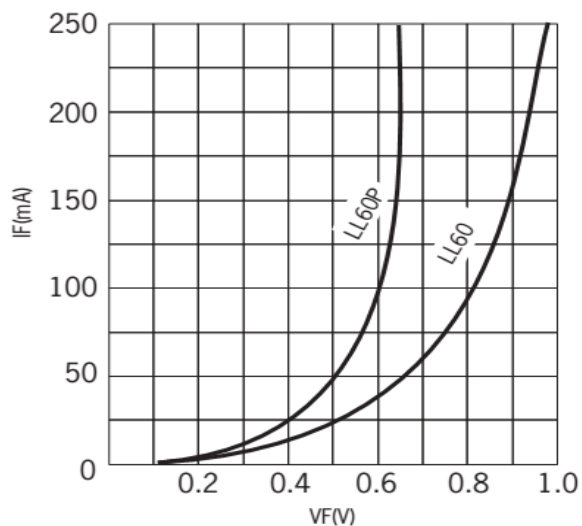


FIG.1 Forward Current vs. Forward Voltage

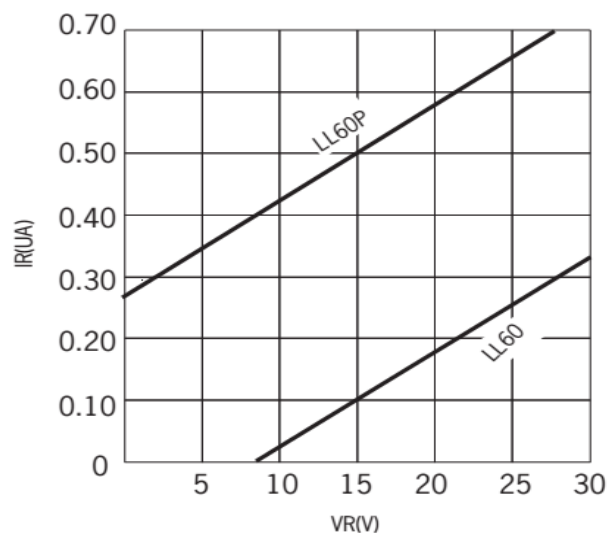


FIG.2 Reverse Current vs. Continuous Reverse Voltage

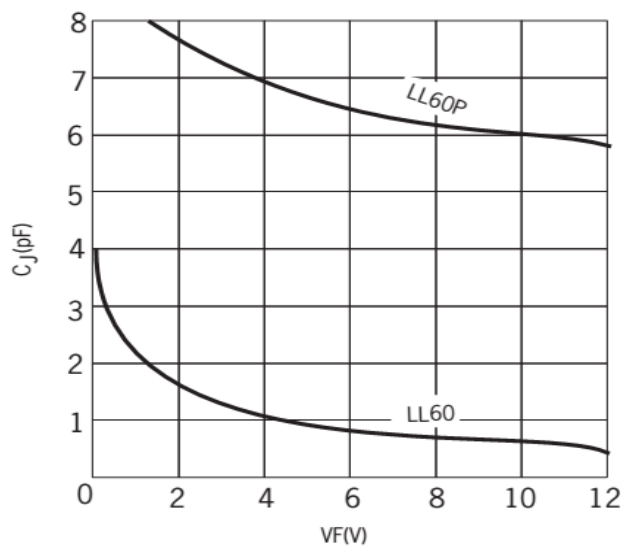
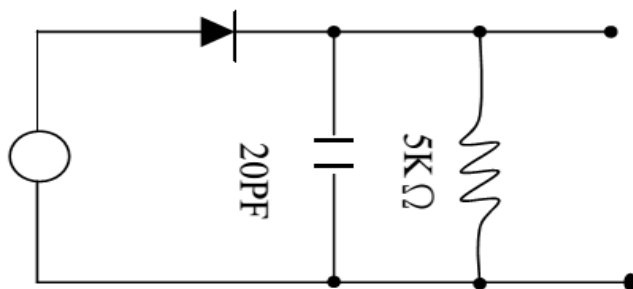


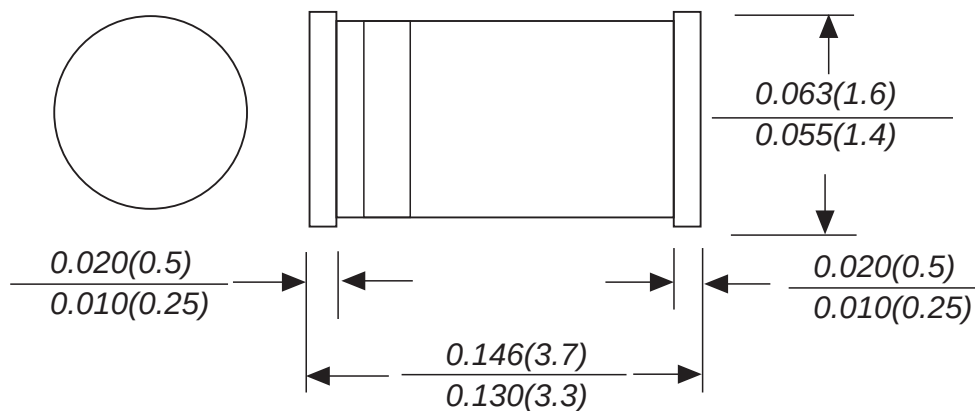
FIG.3 Junction Capacitance vs. Continuous Reverse Applied Voltage



Input 2Vrms

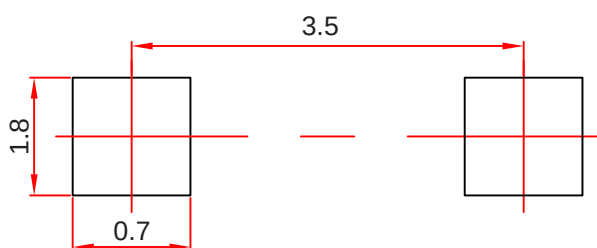
Rectification Efficiency Measurement Circuit

MINI MELF Package Outline Dimensions



Dimensions in millimeters

MINI MELF Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

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